

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner of Patents and Trademarks

Re: Inventors: Byung-Sung Kwak, Jayanthi Pallinti, and William Barth

Title: PROCESS FOR REDUCING IMPURITY LEVELS, STRESS, AND RESISTIVITY, AND INCREASING GRAIN SIZE OF COPPER FILLER IN TRENCHES AND VIAS OF INTEGRATED CIRCUIT STRUCTURES TO ENHANCE ELECTRICAL PERFORMANCE OF COPPER FILLER

Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 17 pages.
☒ Drawings totaling 5 pages, ☒ Formal ☐ Informal.
☒ Signed Declaration and Power of Attorney.
☒ Request and Certification Under 35 U.S.C. 122(b)(2)(B)(i).
☒ Information Disclosure Statement and 12 accompanying disclosures.

22388 U.S. PTO
 10/676934
 093003

FEE CALCULATION

Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	16	-20=	X	x \$18.00	\$0.00
Independent Claims	3	-3=	X	x \$84.00	\$0.00
Multiple Dependent Claim Fee (for one or more)				\$280.00	\$0.00
Basic Filing Fee				\$750.00	\$750.00
TOTAL FEES					\$750.00

Attached is a check in the amount of \$_____.

☒ The Commissioner is hereby authorized to charge \$ 750.00 to Deposit Account No. 12-2252.

☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 12-2252. A duplicate copy of this transmittal is enclosed.

☒ Please address all future correspondence to:

Sandeep Jaggi, Chief IP Counsel
 LSI Logic Corporation
 Legal Department - IP
 1621 Barber Lane, MS D-106
 Milpitas, CA 95035

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on

Respectfully submitted,

Express Mail Receipt No. EU881765873USDate of Deposit September 30, 2003

Signature John P. Taylor
 John P. Taylor



24319

PATENT TRADEMARK OFFICE

John P. Taylor
 John P. Taylor

Patent Attorney
 Registration No. 22,369

**NONPUBLICATION REQUEST
UNDER
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor

Byung-Sung Kwak et al.

Title

PROCESS FOR REDUCING IMPURITY LEVELS,
STRESS, AND RESISTIVITY, AND INCREASING...

Atty Docket Number

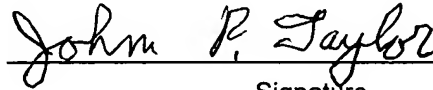
02-5624

I hereby certify that the invention disclosed in the attached application **has not and will not** be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

September 30, 2003

Date



Signature

John P. Taylor

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**